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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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APR 14 2003

In re Application of:

Rome Bloomfield et al.

Serial No.: 10/039,138

Filed: December 31, 2001

For: METHOD AND APPARATUS FOR
GROUNDING A PROCESSOR BOARD

Group Art Unit: 2833

Examiner: Gilman, A.

Atty. Docket: NUHP:0115
200301800-1

TECHNOLOGY CENTER 2800

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JRW
(w-e)Assistant Commissioner
for Patents
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37 C.F.R. 1.8

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April 14, 2003

Date

Tait R. Swanson

Sir:

AMENDMENT AND RESPONSE

In response to the Official Action mailed January 13, 2003, Applicants amend and
remark as follows:

AMENDMENTS

Please amend claim 1 as follows:

1. (Amended) A method of electrically grounding a circuit board to a chassis comprising the steps of:

attaching an electrically conducting mounting stud to chassis;
attaching a ground clip adjacent a mounting hole in the circuit board;
positioning the mounting stud through the mounting hole; and
positively engaging the ground clip with opposite sides of the mounting stud.